

### III. CLAIM AMENDMENTS

1. (Currently Amended) A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

a plurality of wafer supports [connecting] joining the first substantially U-shaped plate to the second substantially U-shaped plate; and

more than two retention springs attached to the first substantially U-shaped plate.

2. (Original) The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a pair of interior arm cutouts.

3. (Original) The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a base cutout.

4. (Currently Amended) The semiconductor cassette reducer of claim 1, wherein a base to tip distance of the first substantially U-shaped plate is less than an interior depth of a front opening unified pod to which the

semiconductor cassette reducer is adapted to be mated.

5. (Original) The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of side panels connected to a pair of arms of the first substantially U-shaped plates.

6. (Original) The semiconductor cassette reducer of claim 5, wherein the pair of side panels have a plurality of lips.

7. (Original) The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has an exterior partial 5-shaped cutout,

8. (Original) The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of columns.

9. (Previously Amended) The semiconductor cassette reducer of claim 8, wherein the pair of columns have at least two positions.

10. (Original) A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate having a first

pair of arms each having a first arm cutout;

a second substantially U-shaped plate having a second pair of arms each having a second arm cutout;

a plurality of wafer supports connecting the first substantially U-shaped plate to the second substantially U-shaped plate.

11. (Original) The semiconductor cassette reducer of claim 10, further including a plurality of retention springs attached to the first substantially U-shaped plate.

12. (Original) The semiconductor cassette reducer of claim 11, wherein one of the plurality of retention springs is designed to mate with a lip of a front opening unified pod.

13. (Original) The semiconductor cassette reducer of claim 10, wherein the plurality of wafer supports include a wafer support panel attached to one of the first pair of arms.

14. (Original) A semiconductor cassette reducer comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

a first wafer support panel attached to a first arm of the first substantially U-shaped plate and to a first arm of the second substantially U-shaped plate; and

a second wafer support panel attached to a second arm of the first substantially U-shaped plate and to a second arm of the second substantially U-shaped plate.

15. (Original) The semiconductor cassette reducer of claim 14, further including a pair of column wafer supports attached to a base of the first substantially U-shaped plate and to a base of the second substantially U-shaped plate.

16. (Original) The semiconductor cassette reducer of claim 14, wherein the first substantially U-shaped plate has a plurality of flexible disks.

17. (Original) The semiconductor cassette reducer of claim 14, wherein the first substantially U-shaped plate has a pair of arms each having an interior cutout,

18. (Currently Amended) The semiconductor cassette reducer of claim 14, wherein a base to tip distance of the first substantially U-shaped plate is less than a diameter of wafer designed for a front opening unified pod to which the semiconductor cassette reducer is adapted to be mated.